

## CoreAXI v3.1 Release Notes

This is the production release for CoreAXI v3.1 IP core. This release notes provides details about the features, supported families, system requirements, implementations, and known limitations and workarounds.

### **Key Features**

Following are the CoreAXI v3.1 features

- Multi-master AXI interconnect with support up to four AXI masters
- All masters support connectivity to all 16 slaves
- Supports additional 17<sup>th</sup> slave when the huge slave or combined region is in use
- Provides 256 bytes to 256 MB of address space for each slave (Huge slave occupies 2 GB address space)
- Supports allocation of slave slots to a combined region slave interface
- AXI interface address width of 32-bits and data bus width of 64-/128-/256-bits
- Supports increment and wrap type bursts
- Round-robin arbitration scheme
- FEED\_THROUGH mode for single slave and single master configuration
- Configurable register pipelining at the input and/or output stage
- The following v2.0 features are retained in v3.1:
  - Support for ID fields to provide additional information on the ordering requirements during read transactions
  - Support for Out-of-Order completion for read transaction. Transaction ordering rules must be followed.
  - Support maximum of four multiple outstanding read transactions to the same slave

## **Delivery Types**

CoreAXI is licensed as a register transfer level (RTL).

#### RTL

Complete RTL source code is provided for the core and test benches.

### Supported Families

- SmartFusion<sup>®</sup>2
- IGLOO<sup>®</sup>2
- RTG4<sup>™</sup>

## **Supported Tool Flows**

Libero System-on-Chip (SoC) software v11.4 or later supports the CoreAXI release.

### Installation Instructions

For the RTL version of the core, the license is not required before the core can be exported.

Consult the Libero SoC online help for instructions on core installation and licensing.



### **Documentation**

This release contains a copy of the *CoreAXI handbook*, which describes the core functionality, gives step-by-step instructions on how to simulate, synthesize, and place-and-route this core, and provides implementation suggestions.

For more information about Intellectual Property, visit: http://www.microsemi.com/products/fpga-soc/design-resources/ip-cores. For updates and additional information about software, FPGAs, and hardware, visit: www.microsemi.com.

# Supported Test Environments

- · Verilog user testbench
- VHDL user testbench

## Release History

There are resolved issues in the v3.1 release.

#### Table 1 Release History

Version	Date	Changes
3.1	April 2015	As listed in Table 2
3.0	May 2014	As listed in Table 3
2.1	September 2013	As listed in Table 4
2.0	January 2013	Initial release

### Resolved Issues in the v3.1 Release

#### Table 2 Resolved SARs in CoreAXI v3.1 Release

SAR	Description	
66253	Add support for RTG4	
63022	CoreAXI display name should arguably be "CoreAXI" and not "COREAXI"	
57930	Typos in Temp grade metadata	

### Resolved Issues in the v3.0 Release

#### Table 3 Resolved SARs in CoreAXI v3.0 Release

SAR	Description	
53137	Add support for 128-bit and 256-bit data widths	
53138	Add multi-master support	
53435	Slave address space needs to be increased above, 256 MB	

## Resolved Issues in the v2.1 Release

#### Table 4 Resolved SARs in CoreAXI v2.1 Release

SAR	Description	
49706	Misc packaging issues for CoreAXI 2.0.104	
50274	CoreAXI does not pass write data through write data channel	
50407	CoreAXI version 2.0.104 does not work in either HDL sim or on hardware	



# **Discontinued Features and Devices**

There are no discontinued features for release of CoreAXI v3.1 release.

## **Known Limitations and Workarounds**

- Write data interleaving and write data out-of-order is not supported.
- Outstanding write transactions are not supported.
- The low power interface of AXI is not supported.
- Outstanding read transactions to different slave with the same ID value are not supported.
- Outstanding read transactions to different slave with different ID value are not supported.
- Only four ID values are available per master.



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